

아크릴 실란 가교제를 사용한 도로 표시용 실온 경화 아크릴 바인더의 특성

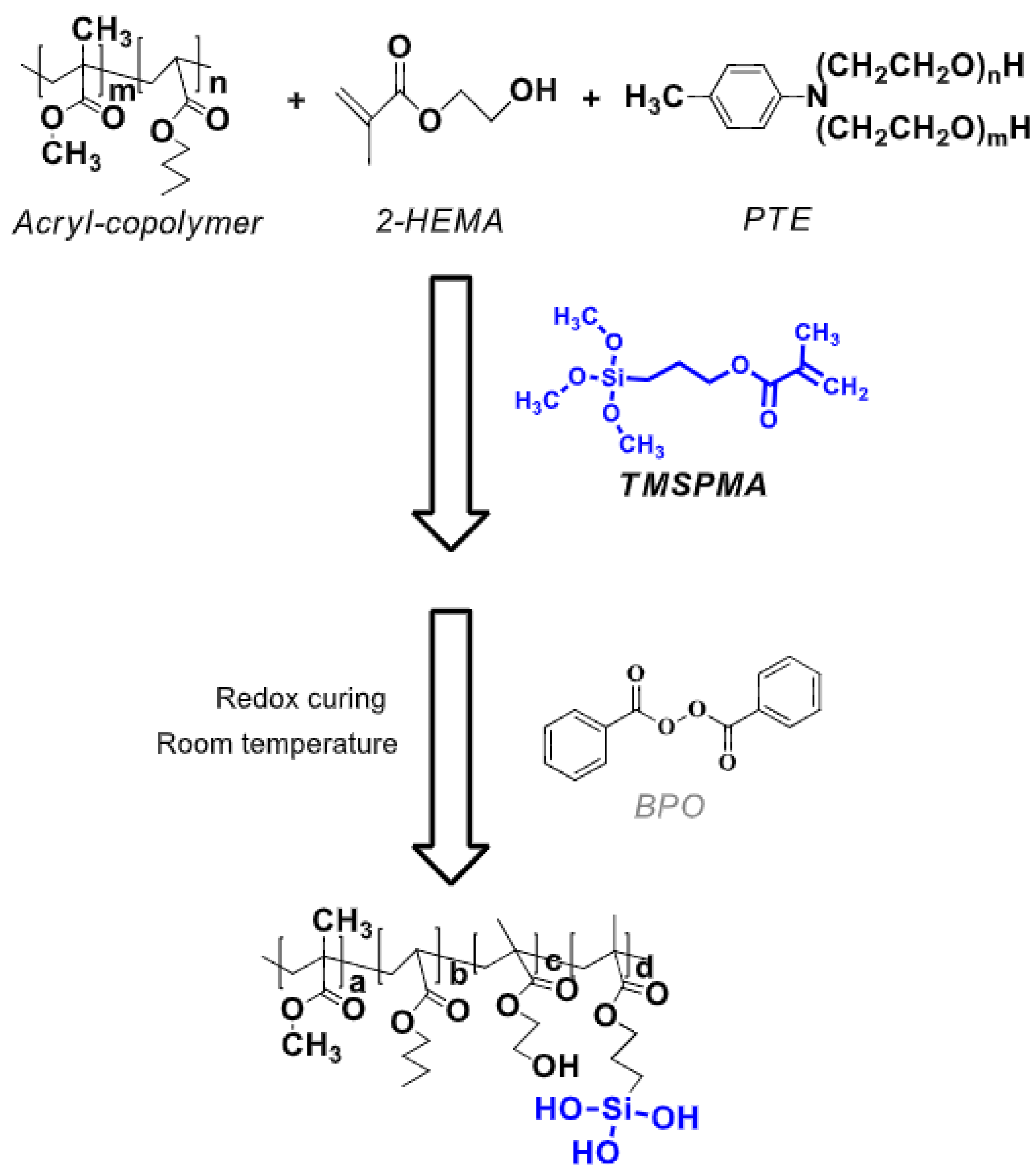
Characteristics of room temperature curing acrylate binders for road markings using acrylic silane crosslinkers

Jae-Ryong Lee, Won-Bin Lim, Jin-Gyu Min, Ju-Hong Lee, Keun-Ho Lee, Ha Song Bong, Sang Wook Byun, Ji-Hong Bae, and Pil Ho Huh*
Department of Polymer Science and Engineering, Pusan National University, Busan 46241, South Korea
* pilho.huh@pusan.ac.kr

Abstract

부틸아크릴레이트(BA), 메틸메타크릴레이트(MMA), 2-하이드록시에틸메타크릴레이트(2-HEMA), 3-(트리메톡시실릴)프로필메타크릴레이트(TMSPMA) 및 첨가제를 사용하여 복합구조 도로 마킹용 고성능 아크릴 수지를 합성하였다. 제조된 수지는 산화환원개시제 시스템(ROIS)을 사용하여 실온에서 경화시켰다. TMSPMA 함량 변화를 비교한 결과, 함량이 증가함에 따라 수지의 주쇄 구조 내 가교 네트워크가 최적화되어 접착력과 투과성이 모두 향상되는 것으로 나타났다. 이러한 아크릴 수지의 기계적 및 형태적 특성은 만능 시험기(UTM), UV 분광법, 주사전자현미경(SEM)을 사용하여 종합적으로 평가하였다.

Experimental



Experimental

Step 1 Blend Acrylic monomer and catalyst

Step 2 Add initiator and Stir

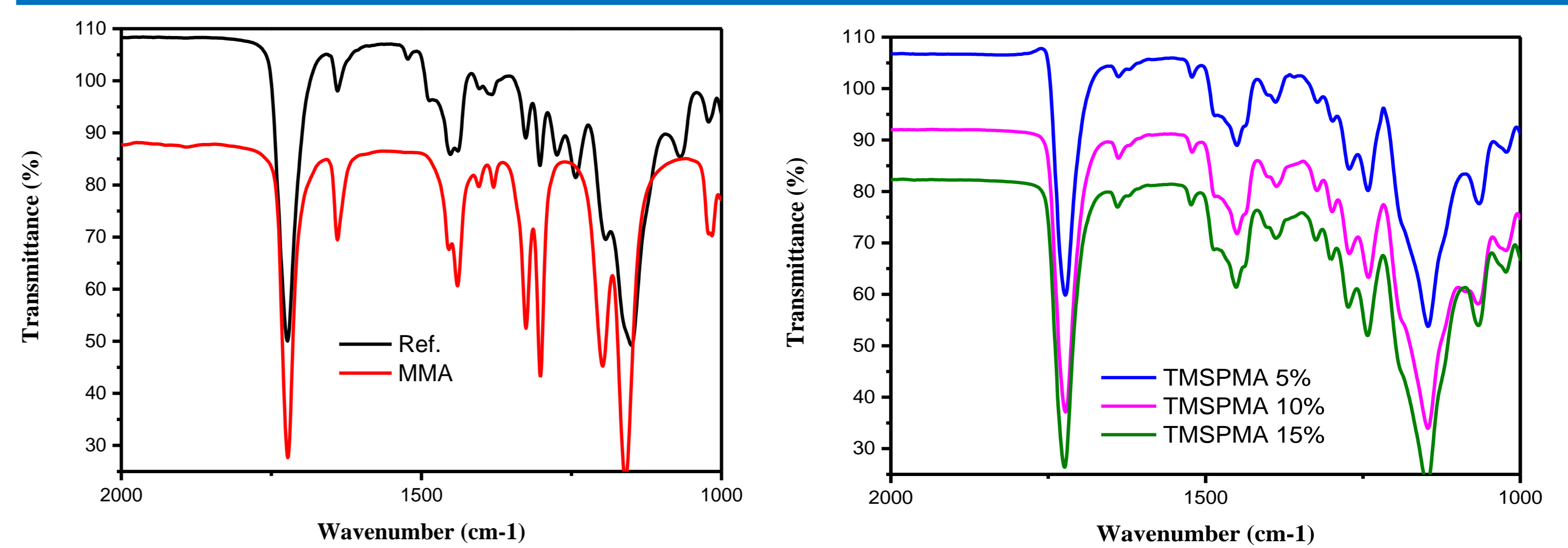
Step 3 Apply adhesive to specimen

Contents table

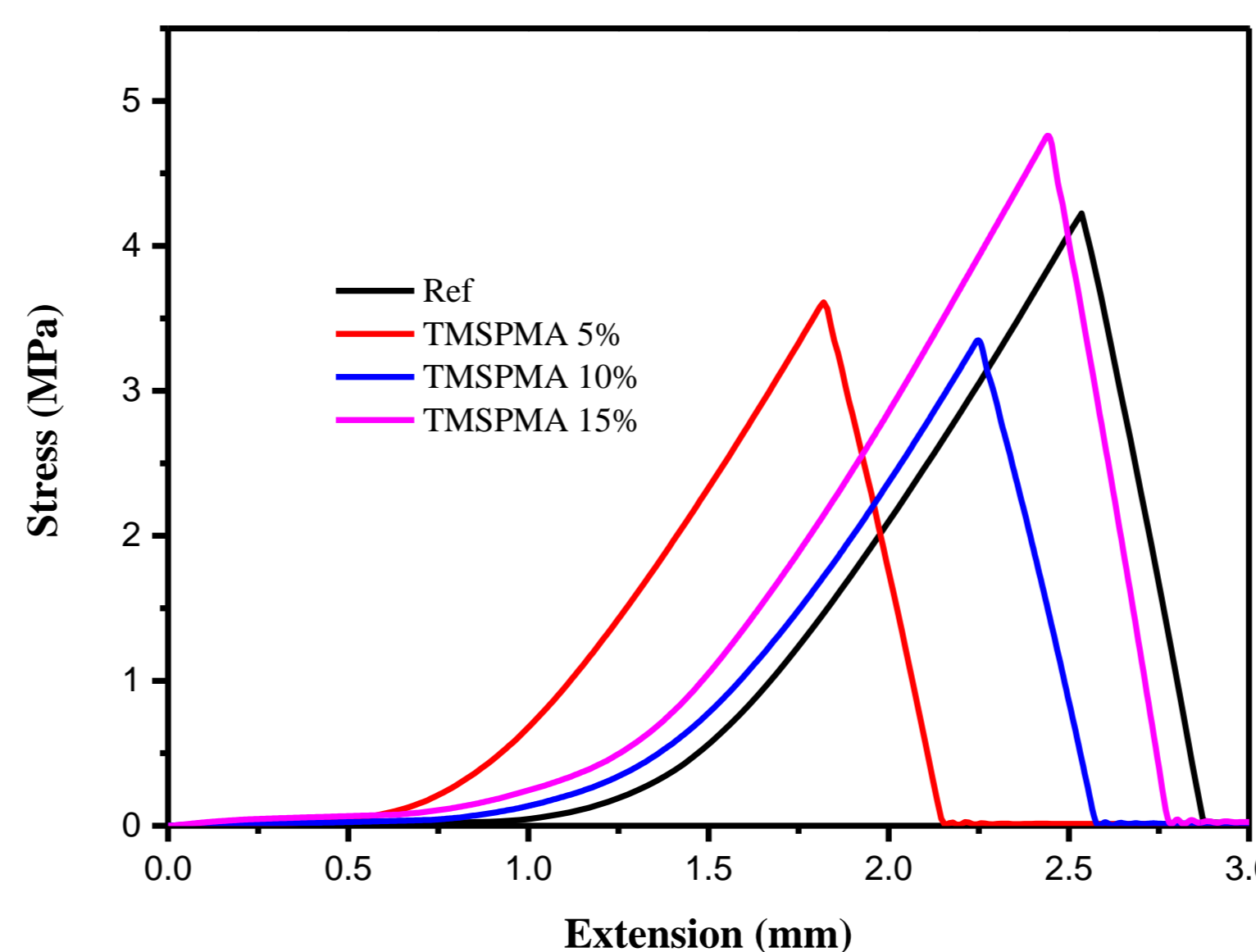
SAMPLE	Ref (wt%)	Sample (wt%)
Reference	1	0
TMSPMA 5%	0.95	0.05
TMSPMA 10%	0.9	0.1
TMSPMA 15%	0.85	0.15

Results

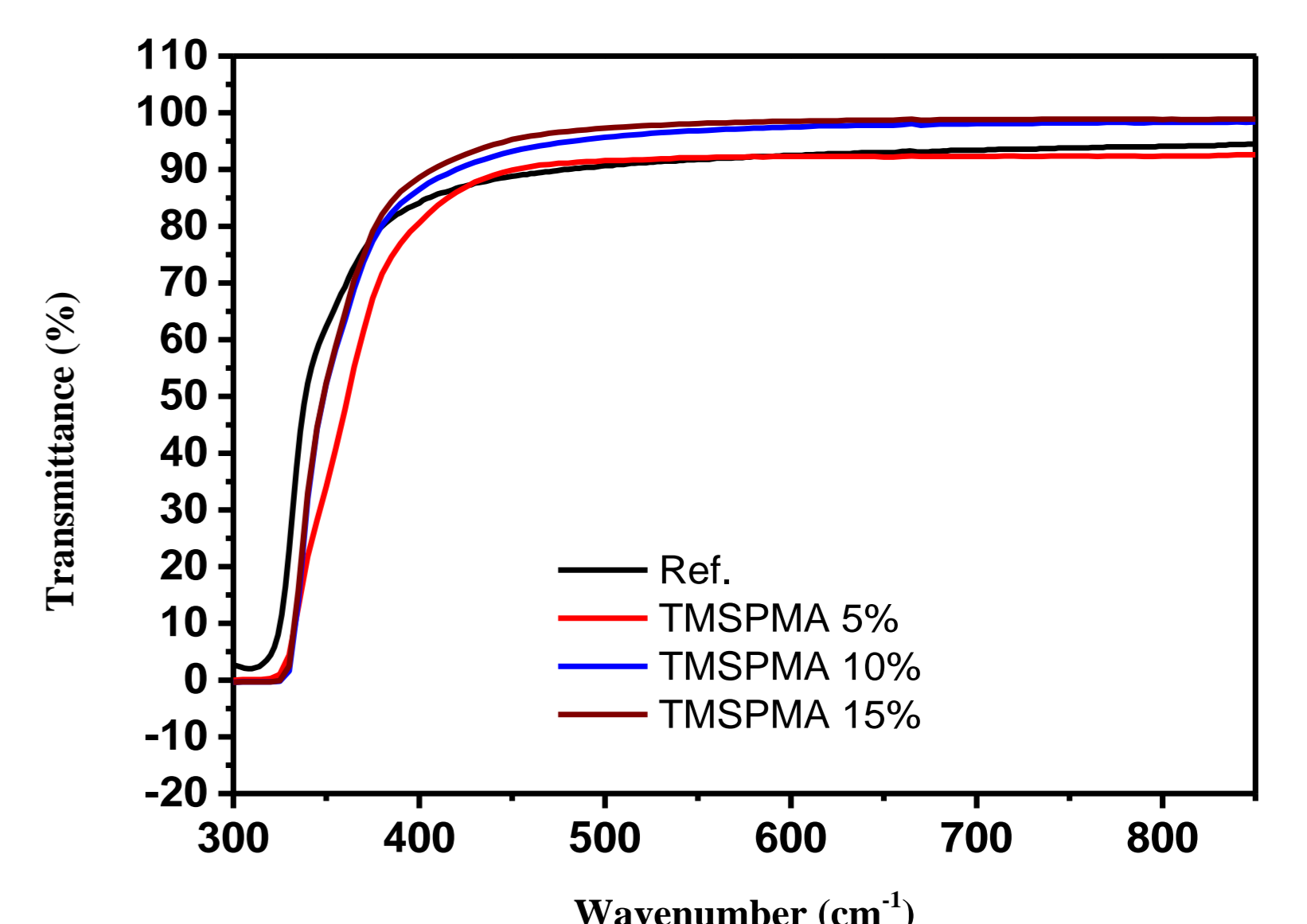
FT-IR



UTM



Transmittance



SAMPLE	Peak strength
Reference	4.223
TMSPMA 5%	3.61
TMSPMA 10%	3.34
TMSPMA 15%	4.75

SAMPLE	Peak strength
Reference	4.223
TMSPMA 5%	3.61
TMSPMA 10%	3.34
TMSPMA 15%	4.75

Conclusion

- Polymerization was confirmed by decreasing the peak of C=C at 1640 cm⁻¹ according to radical reaction through FT-IR
- Transmittance increases as the content of TMSPMA increases.
- Contact angle increases to 10 % of TMSPMA content, and the contact angle decreases from 10 % of TMSPMA content.
- Peak strength decrease to 10 % of TMSPMA content, and the peak strength increases from 10 % of TMSPMA content.
- As Wettability increases, Adhesion Strength increases. Proper content is important.

Acknowledgement

This work was supported by the Korea Institute of Industrial Technology Evaluation and Planning (KEIT) in 2024 (00433823, Production technology development of bio polyamide66 advanced materialproduct based on starch(sugar) byproducts for future transport internal&external components/modules).